

VERSION WITH MARKINGS TO SHOW CHANGES MADE

Claims 1 and 12 have been rewritten and claims 21-30 have been canceled.

1. (Twice Amended) A semiconductor device comprising:

a solder mask;

a die; and

an adhesive layer between said die and said solder mask, wherein said adhesive layer comprises a material that remains voidless after outgassing from said solder mask and is at least partially curable at a temperature below about 100°C.

12. (Twice Amended) A semiconductor device comprising:

a solder mask;

a die;

electrical contacts on said solder mask and said die, each said contact on said die being wire bonded to a respective said contact on said mask, said electrical contacts being devoid of contamination caused by outgassing from said solder mask; and

an adhesive layer affixing said die to said solder mask, said adhesive layer comprising a material that is curable at a temperature below about 100°C and at a temperature between about 20°C and about 50°C higher than a glassy temperature of said adhesive layer.

Claims 21-30 have been canceled.